

Type number	Package	Package description	Total product weight
74AUP1G04GN	SOT1115	X2SON6	0.86666 mg

12NC	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	RHF-indicator
		MSL	PPT	MPPT	MSL	PPT	MPPT			
935291714132	6	1	260	30 s	1	240	20 s	3	Bangkok, Thailand; Seremban, Malaysia; Nijmegen, Netherlands	

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of subpart	Mass(%) of total product
Die	Doped silicon	Silicon (Si)	7440-21-3	0.03146	100.00000	3.62945
		subTotal		0.03146	100.00000	3.62945
Component	Additive	Non hazardous	Proprietary	0.00025	5.00000	0.02885
	Filler	Bisphenol-A/Epichlorohydrin Epoxy resin (generic)	25068-38-6	0.00025	5.00000	0.02885
		Silica -amorphous-	7631-86-9	0.00250	50.00000	0.28846
	Polymer	Epoxy resin system	Proprietary	0.00150	30.00000	0.17308
		Phenol Formaldehyde resin (generic)	9003-35-4	0.00050	10.00000	0.05769
		subTotal		0.00500	100.00000	0.57693
Lead Frame	Copper alloy	Copper (Cu)	7440-50-8	0.36386	94.51000	41.98457
		Magnesium (Mg)	7439-95-4	0.00058	0.15000	0.06664
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01136	2.95000	1.31049
		Silicon (Si)	7440-21-3	0.00246	0.64000	0.28431
	Pure metal layer	Gold (Au)	7440-57-5	0.00008	0.02000	0.00888
		Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.00631	1.64000	0.72854
		Palladium (Pd)	7440-05-3	0.00035	0.09000	0.03998
subTotal		0.38500	100.00000	44.42341		
Mould Compound	Additive	Misc. Phosphor compounds (generic)	7723-14-0	0.00044	0.10000	0.05019
		Non hazardous	Proprietary	0.01566	3.60000	1.80694
	Filler	Silica fused	60676-86-0	0.38280	88.00000	44.16957
	Pigment	Carbon black	1333-86-4	0.00087	0.20000	0.10039
		Phenolic resin	Proprietary	0.01784	4.10000	2.05790
	Polymer	Tetramethylbiphenyl diglycidyl ether	85954-11-6	0.01740	4.00000	2.00771
subTotal			0.43500	100.00000	50.19270	
Wire	Gold alloy	Gold (Au)	7440-57-5	0.01011	99.00000	1.16631
		Palladium (Pd)	7440-05-3	0.00010	1.00000	0.01178
	subTotal		0.01021	100.00000	1.17809	

Note(s):

1) This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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